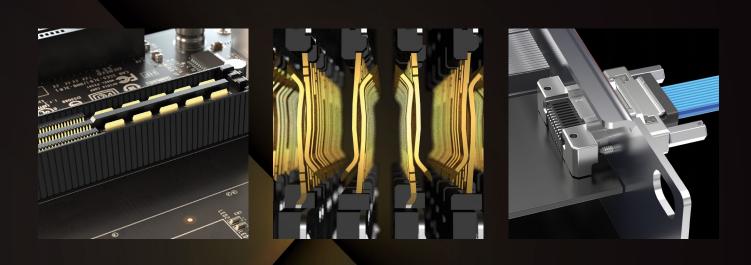


RUGGED HIGH-SPEED INTERCONNECT SOLUTIONS



Performance & Reliability for the Most Demanding Applications

RUGGED HIGH-SPEED INTERCONNECT SOLUTIONS

Samtec offers a robust line of high-speed interconnect systems that are optimized for performance, durability and reliability in the most demanding environments.



APPLICATIONS & INDUSTRIES









Automotive

Medical Mil/Aero Industrial



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RUGGED HIGH-SPEED SYSTEMS

PANEL & MID-BOARD CABLE SYSTEMS

- URSA® I/O features Hyper Claw™ contacts; 1 to 5 banks with high-speed, RF and power configurations in development
- NovaRay® I/O bulkhead or threaded 38999 panel connection
- ExaMAX® I/O features a fully shielded external cable and cage
- AcceleRate® features a slim body with integrated guide posts
- EMI shielding limits signal degradation, optimizes performance
- Ruggedizing features include captive panel screws, strain relief, pull latches, slim latching, and guide posts for blind mating
- SI Evaluation Kits available, visit samtec.com/kits













 ${\sf EXAMAX}^{\texttt{@}} \ is \ a \ registered \ trademark \ of \ Amphenol \ FCI \ Asia \ Pte. \ Ltd. \ Used \ with \ permission.$

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BOARD-TO-BOARD & BACKPLANE SOLUTIONS

- SEARAY[™] high-density arrays offer the most power versatility
- AcceleRate® mP best in class density for power and signal
- ExaMAX® & NovaRay® backplane systems offer two reliable points of contact
- Edge Rate® strips optimized for high performance and cycles
- Generate® edge cards with signal/power and tucked beam options
- Q Series® with integral ground/power plane for reliable SI/power
- Razor Beam[™] self-mating interfaces reduce inventory costs
- SI Evaluation Kits available, visit samtec.com/kits













RUGGEDOPTIONS

360° EMI Shielding Metal Latching Extended Guide Posts Friction/Board Locks Weld Tabs











RUGGED HIGH-SPEED SYSTEMS

PRECISION RF SOLUTIONS

- Magnum RF® ganged, multi-port blocks and cable assemblies feature a push-on SMPM interface with varying retention forces
- Nitrowave[™] high-performance microwave cable assemblies are phase and amplitude stable with flexure; dynamic performance layer (DPL) minimizes loss and improves stability
- Rugged U.FL/MHF* 1 cable assemblies with metalized strain relief for increased durability; 500 mating cycles
- VITA[™] 90 VNX+[™] solutions with rugged blind mate RF modules, SEARAY[™] right-angle array and rugged optics; enables SWaP-C reductions
- Custom and quick turn modifications available













MHF® is a registered trademark of I-PEX® Inc. MTP® and MXC® are registered trademarks of US Conec Ltd. VITA/VNX/VNX+ are all respective trademarks of VITA.

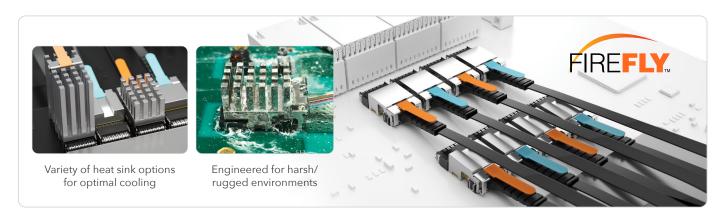


MID-BOARD OPTICAL TRANSCEIVERS

- FireFly™ EXT with an extended temperature range of -40 °C to +85 °C
- FireFly™ EET features a parylene conformal coating for extreme environments; tin whisker mitigation, and salt fog resistance capabilities
- Halo® optical transceivers are designed for next gen embedded applications, and withstand high shock and vibration in a low 6.35 mm profile for space savings
- SWaP optimized designs for longer connections
- Multiple end options, including MTP*, MXC*, MT, and a variety of rugged interfaces
- SI Evaluation Kits available, visit samtec.com/kits









Variety of heat sink options for thermal relief



E.L.P.™ & SET certified AcceleRate® contacts for rugged applications



RUGGED END OPTIONS



Amphenol® MT38999



VITA[™] 66.1/66.4 Interface



Glenair® Series 79 MT Connector

ULTRA RUGGED OPTIONS

Most Samtec interconnect systems are available with a variety of standard and optional features, plus hardware and coatings, to further ensure quality and durability in rugged and harsh environments. For added reliability, Samtec also offers rugged contact systems designed to support high-speed performance, as well as high mating cycles and high-shock/vibration applications.

RUGGEDIZING OPTIONS



LATCHING

Manually activated latches increase unmating force by up to 200%



Metal or plastic friction locks increase retention/withdrawal force



STRAIN RELIEF

Helps protect against lamage caused by frequent movement, strain or stress





Significantly increases shear resistance of connector to PCB







RUGGED/HIGH-RELIABILITY CONTACT SYSTEMS



EDGE RATE*
Designed for signal integrity
Superior impedance control
Reduced broadside coupling



HYPER CLAW™ Micro hyperboloid contact our reliable points of contact Extreme mating cycles



EXAMAX*
Two reliable points of contact
2.40 mm mating surface area
Excellent contact normal force



ACCELERATE*

Designed for highperformance & reliability

SET & E.L.P.™ qualified

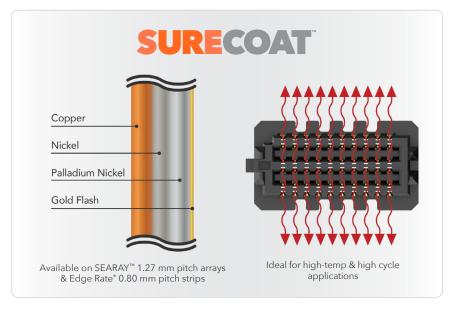


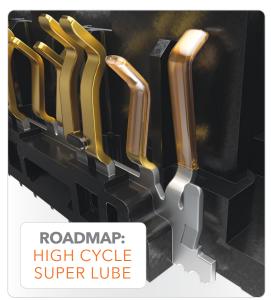
PRECISION HARDWARE & NEXT GEN MATERIALS

- Guide post standoffs allow for .035" of initial misalignment and blind mate
- Jack screw precision standoffs reduce component damage
- Standoffs with precision machined tolerances (+/- 0.50 mm)
- Guide post with built in grounding pin available for first mate last break applications
- SureCoat[™] high-reliability 30 μ " palladium nickel plating with gold flash; qualified to 150 °C ambient and 5,000 cycles
- Power guide posts, with Hyper Claw[™] contacts, pair with high-speed connectors for a power/signal solution; in development, contact RuggedPower@samtec.com
- Roadmap: High cycle super lube withstands reflow and extreme mating cycles, provides increased corrosion resistance; contact RuggedPower@samtec.com









ULTRA RUGGED TESTING

SEVERE ENVIRONMENT TESTING (SET) | SAMTEC.COM/SET

Additional testing beyond typical industry standards for performance confidence in military, space, automotive, industrial and other extreme environment applications. Qualified products are Commercial Off-the-Shelf (COTS) and modified COTS for quick-to-market solutions. Please visit samtec.com/SET or contact SET@samtec.com for more information and test results.



	VITA™ STANDARD	MEETS	EXCEEDS
	Module Insertions	✓	
	Operating Shock Class OS2	✓	
	Vibration Class VS3	1	
47.1	Electrostatic Discharge Resistance	✓	
	Temperature Cycling Class C4		✓
	Non-Operating Temp Class C4		✓
	Altitude for DWV		1
47.3	Humidity	1	

QUALIFIED SERIES	PITCH	ТҮРЕ
LSHM	0.50 mm	Razor Beam™ Hermaphroditic Strips
ERF8/ERM8	0.80 mm	Edge Rate® Rugged, High-Speed Strips
SEAF8/SEAM8	0.80 mm	SEARAY™ 0.80 Ultra-High Density Arrays
B1SDT/P1M	1.00 mm	URSA® I/O Ultra Rugged Cable System
SFM/TFM/SFSDT	1.27 mm	Rugged Tiger Eye™ Connectors
SEAF/SEAM	1.27 mm	SEARAY™ High-Density Arrays
FTSH/CLP	.050"	Flexible Stacking Header & Socket
S2M/T2M	2.00 mm	Tiger Eye™ Micro Rugged System
UMPS/UMPT	2.00 mm	mPOWER® Ultra Micro Power Connectors
SSM/TSM	.100"	Square Post Header & Socket











LOT SCREEN TESTING

This program provides assurance for upscreening board-to-board interconnects for mission critical applications. Lot Screen Testing and Qualification Conformance Inspection (QCI) are both modeled after MIL-DTL-55302 and parallel EIA-364 standards. Contact map@samtec.com or visit samtec.com/mil-aero for details.

NASA-ALIGNED SOLUTIONS

SET products are approved for NASA Class D missions including LEO satellites, SmallSats, CubeSats and other space exploration applications. NASA outgassing data is used to determine if certain products meet ASTM E595-77/84/90 requirements. Visit outgassing.nasa.gov.

TESTING OPTIONS	LOT SCREEN	QCI
restinte of florts	TESTING	46.
Visual & Mechanical Inspection	✓	✓
Mating/Unmating Forces	✓	✓
Low Level Contact Resistance	✓	✓
Insulation Resistance	(Pin-to-Pin & Row-to-Row)	(Pin-to-Pin, Row-to-Row & Closest Metallic Hardware)
Dielectric Withstanding Voltage	(Sea Level)	(Sea Level & High Altitude)
Solderability	1	√
Contact Resistance	✓	✓
Mechanical Shock		✓
Random Vibration		✓
Extended Life		(Plating Thickness Verification, Mating Cycle, Thermal Shock, Humidity)
Workmanship		✓

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EXTENDED LIFE PRODUCT™ (E.L.P.™) | SAMTEC.COM/ELP

 $E.L.P.^{TM}$ Products are tested to rigorous standards, which evaluate contact resistance in simulated storage and field conditions.

- 10 year Mixed Flowing Gas (MFG)
- High Mating Cycles (250 to 2,500)
- Certain plating and/or contact options will apply

For complete details about Samtec's E.L.P.™ program, a list of qualifying products and test results, please visit **samtec.com/ELP** or email the Customer Engineering Support Group at **ASG@samtec.com**.









DESIGN QUALIFICATION TESTING (DQT)

All Samtec series undergo Design Qualification Testing, which includes:

- Gas Tight
- Normal Force
- Thermal Aging
- Mating/Unmating/Durability
- IR/DWV

- Current Carrying Capacity (CCC)
- Mechanical Shock/Random Vibration/LLCR
- Mechanical Shock/Random Vibration/Event Detection



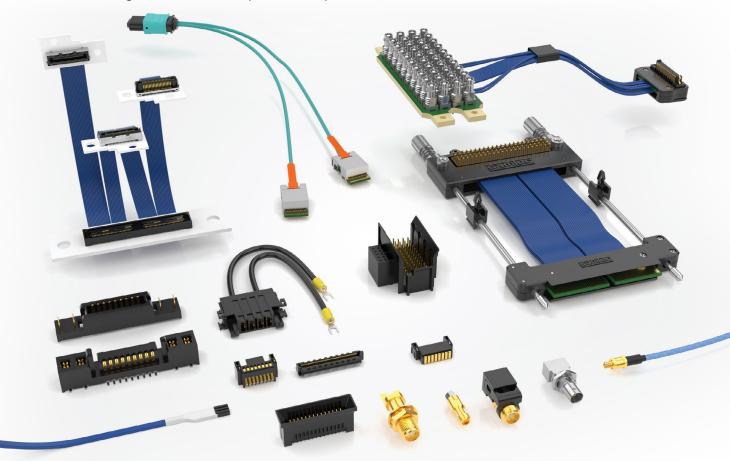
TESTING REFERENCE CHART

TYPE OF TEST	SET	E.L.P.™	DQT
Gas Tight	✓*	✓*	✓
Normal Force	√ *	√ *	✓
Thermal Aging	√ *	√ *	✓
Mating/Unmating/Durability (240 Hrs)	(100% RH, 250 Cycles)	/ * (90-98% RH, 100 Cycles)	(90-98% RH, 100 Cycles)
IR/DWV	(At Altitude of 70,000 Feet)	✓ *	✓
ccc	✓ *	✓ *	✓
Mechanical Shock/Random Vibration/ LLCR & Nanosecond Event Detection	(40 G Peak, 11 ms, Half Sine & 12gRMS, 5 - 2,000 Hz, 1 Hr / Axis)	/* (100 G Peak, 6 ms, Half Sine & 7.56gRMS Avg, 2 Hr / Axis)	(100 G Peak, 6 ms, Half Sine & 7.56gRMS Avg, 2 Hr / Axis)
Temperature Cycling (500 Cycles)	✓	N/A	N/A
Non-Operating Class Temperature	✓	N/A	N/A
Electrostatic Discharge (ESD)	✓	N/A	N/A
10 Year MFG (Mixed Flowing Gas)	N/A	✓	N/A
Mating Cycles (250 to 2,500)	N/A	✓	N/A

^{*} Completed as part of initial Design Qualification Testing (DQT). E.L.P. $^{\text{\tiny{M}}}$ and SET testing are performed in addition to DQT.

CUSTOMS & EXPRESS MODIFICATIONS

Samtec's industry-leading customer service, signal integrity expertise, and our flexible, in-house manufacturing capabilities allow us to provide new and/or completely custom designs, as well as common simple modifications to standard products - often with low or no NRE charges, short lead times, quick-turn samples, and low or no MOQ's.



RUGGEDIZING FEATURES

- Contacts & bodies
- Stamping, plating & molding
- Screw downs
- Latches & locks
- Shielding modifications
- Polarization

RF

- Board termination types
- Tin dipping capabilities
- Automated assembly counterweights
- Heat-shrink tubing
- Alternate platings
- Pick & place machine designs
- RFGroup@samtec.com

HIGH-SPEED CABLE

- Contacts
- Wiring
- Packaging
- Bodies
- Strain relief
- Labeling
- Ink printing
- HDR@samtec.com

OPTICS

- Parylene coating
- Mitigation for tin whiskers
- Custom or secure firmware
- Custom optical connectors
- Custom fiber mapping
- Custom optical link budget
- Custom assemblies with multiple FireFly™ optical connectors
- OpticsOTP@samtec.com

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SPACE HERITAGE (INDUSTRY STANDARDS)

For 25+ years, Samtec has been developing products and supporting standards for systems that launch into space. The first stage of Samtec's space heritage began when one of Samtec's earliest products, SamArray* High-Density Open-Pin-Field Array, was selected as part of the VITA $^{\text{m}}$ 42 XMC $^{\text{m}}$ standard in 2002.

Since then, Samtec engineers have continued to engage with numerous standards bodies to develop the standards and interconnects that make leading-edge space-qualified designs possible and continue to expand on Samtec's space heritage.

2002 VITA™ 42 XMC™ STANDARD Samtec's SamArray® Open-Pin-Field Arrays with solder ball technology are specified for the VITA™ 42 XMC™ standard. Applications: mil/aero, embedded computing, signals intelligence (SIGINT), image processing. 2004 SEARAY™ HIGH-DENSITY ARRAYS Samtec's SEARAY™ Open-Pin-Field Array is released. The high-speed, high-density connector features a rugged contact system, lower insertion/ withdrawal forces and maximum grounding and routing flexibility. 2007 VITA™ 57.1 FMC™/57.4 FMC+™ STANDARDS SEARAY™ High-Density Open-Pin-Field Arrays are selected for VITA™ FMC[™] & FMC+[™] standards. Applications: avionics/payload subsystems, signal processing, vision, AI and small chassis radar. 2010 FIREHAWK® OPTICAL TRANSCEIVERS Rad-Hard Compact, Lightweight Optical Mid-Board Transceivers are released. Applications: satellite, radar, vision systems, communications, surveillance and reconnaissance. 2019 VITA™ 88 XMC+™ STANDARD **SEARAY**[™] **High-Density Open-Pin-Field** high-pin-count connectors are specified for the XMC+™ standard. Applications: small chassis radar systems, data acquisition, SpaceCube™ v2.0 mini. 2022 **EXTENDED TEMP FIREFLY™ OPTICS** Samtec's FireFly™ Mid-Board Optical Transceiver family is expanded to include an extended temperature range design, ideal for harsh environments with high radiation potential. VITA™ 90 VNX+™ STANDARD **SEARAY**[™] **High-Pin-Count, Right-Angle Connector** is specified for the VNX+™ standard. Applications: space-constrained deployments, compute modules, SDR modules, tactical grade sensors. **ACCELERATE® SLIM DIRECT ATTACH CABLE SYSTEM** AcceleRate® Slim, High-Performance Cable developed. Optional rugged screw down retention and external shielding provide EMI protection; Tin/Lead plating and low-outgassing materials meet LEO specifications.

 $\label{lem:VITA_VIX} VITA/VNX+/FMC/FMC+/XMC/XMC+ are all respective trademarks of VITA.$

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SIGNAL INTEGRITY EXPERTISE

Samtec is the industry leader in Signal Integrity. Offering unparalleled support for all aspects of high-performance system design, our mission is to help ensure full system optimization – from Silicon-to-Silicon $^{\text{\tiny{M}}}$. For assistance with your application, contact the Signal Integrity Group at sig@samtec.com.

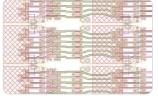


FULL SYSTEM SIGNAL INTEGRITY OPTIMIZATION

Samtec provides industry-leading SI expertise, both at the component and system level, to ensure optimized performance throughout the entire high-speed system.

- High-performance system architectures and design solutions
- PCB/BOR layout and routing recommendations
- System level design support for full channel SI optimization
- High-performance interconnect selection assistance

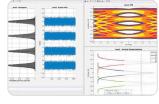




SIGNAL INTEGRITY TESTING, ANALYSIS & EVALUATION

Leveraging the industry's leading software and hardware, along with expertise in Signal Integrity, enables Samtec to provide reliable data for the evaluation of high-performance systems.

- 3D signal integrity modeling and simulation
- Qualification and characterization testing/test reports
- Support and tools for full-channel simulation and analysis
- Signal integrity evaluation boards and development kits



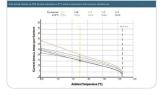


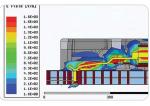


PDN / THERMAL MODELING, TESTING & SIMULATION

Samtec engineers offer complete support for testing, evaluating and optimizing challenging thermal and power considerations of high-performance system designs.

- Power and thermal modeling, simulation and characterization
- Power integrity characterization test reports
- Analysis/optimization of PDN components and sub-components
- Testing/qualification for application-specific requirements



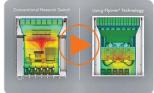




POWER ARCHITECTURE SYSTEM DESIGN & ROUTING SUPPORT

Samtec provides complete design and development support, routing strategies and recommendations for the optimization of system power architectures.

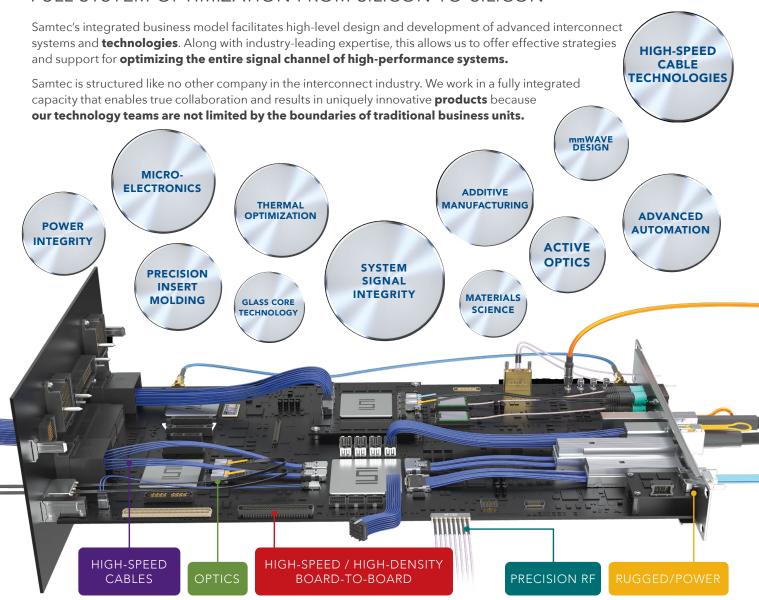
- System power architectures and design solutions
- Reference routing development for application-specific solutions
- Safety and reliability design assurance
- Recommendations for customer-specific requirements



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INTEGRATION LEADS TO INNOVATION

FULL SYSTEM OPTIMIZATION FROM SILICON-TO-SILICON™



SILICON-TO-SILICON™ SOLUTIONS

NEXT GENERATION CONNECTIVITY TO 224 Gbps & BEYOND

As bandwidth, scale and power requirements continue to challenge conventional engineering methods, Samtec strives to help **optimize the landscape of your entire system** - and develop solutions, together.

Samtec's industry-leading signal integrity expertise, full system optimization strategies, and innovative products and technologies help address the challenges of **next gen data transmission to 224 Gbps & beyond.**

GLOBAL SUPPORT & SERVICE



Technical Support

Signal Integrity Group: sig@samtec.com

Application Support Group:

Interconnect Processing Group: ipg@samtec.com

Supply Chain Support

MySamtec™ Real-Time Account Access: account.samtec.com

Personal Account Managers/CSRs:

Upfront, Aggressive 24-Hour Quotes: ePricing@samtec.com



More than 200,000 Part Numbers Ship in 1 Day



24-Hour Free Samples



2 Day Transit to All Major Markets



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